

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chin-Ming LIN	05/10/2012
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13476290
CORRESPONDENCE DATA	
Fax Number:	(703)518-5499
Phone:	7036841111
Email:	tsmc@ipfirm.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Lowe Hauptman Ham & Berner, LLP (TSMC)
Address Line 1:	1700 Diagonal Road, Suite 300
Address Line 4:	Alexandria, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	T5057-753
NAME OF SUBMITTER:	Randy A. Noranbrock
Total Attachments: 1 source=efiledassgn#page1.tif	

OP \$40.00 13476290

Docket No. T5057-753
TSMC2011-1401

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Chin-Ming LIN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SELECTIVE SOLDER BUMP FORMATION ON WAFER

(a) for which an application for United States Letters Patent was filed on 2012-05-21, and identified by United States Patent Application No. 13/476,290; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chin-Ming Lin
Name: Chin-Ming LIN

May. 10. 2012
Date: